AMENDMENTS TO THE CLAIMS

1. **(Previously presented)** A chemically amplified positive photosensitive thermosetting resin composition comprising:

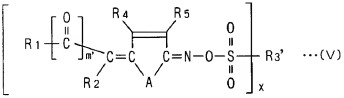
a reaction product of (A) an alkali soluble resin having a phenolic hydroxyl group and (C) a crosslinking polyvinyl ether compound;

(B) a compound generating an acid under irradiation with radiation; and

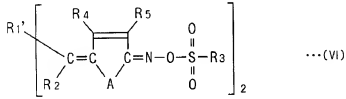
(D) an epoxy resin.

2. **(Currently amended)** A chemically amplified positive photosensitive thermosetting resin composition comprising (A) an alkali soluble resin, (B) a compound generating an acid under irradiation with radiation, (C) a crosslinking polyvinyl ether compound, and (D) an epoxy resin,

wherein (B) represented by the following general formulas (V), (VI), ~~(VII)~~ or (X):

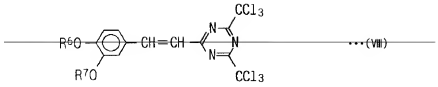


...(V)



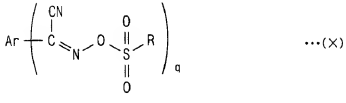
...(VI)

[wherein m' represents 0 or 1; X represents 1 or 2; R_1 is a phenyl group which may be substituted with one or more C_1-C_{12} alkyl groups, or a heteroaryl group, or, when m' is 0, R_1 may further be a C_2-C_6 alkoxycarbonyl group, a phenoxycarbonyl group or CN; R_1' represents a C_2-C_{12} alkylene group; R_2 has the same meaning as in R_1; R_3 represents a C_1-C_{18} alkyl group; R_3' has the same meaning as in R_3 when X = 1, or a C_2-C_{12} alkylene group or a phenylene group when X = 2; R_4 and R_5 each independently represents a hydrogen atom, a halogen, or a C_1-C_6 alkyl group; A represents S, O or NR_6; and R_6 represents a hydrogen atom or a phenyl group],



[~~wherein R^6 and R^7each represents an alkyl group having 1 to 3 carbon atoms, or a combination of the compound (VIII) and a bis(trichloromethyl)triazine compound represented by the following formula (IX):~~

~~wherein Z represents a 4-alkoxyphenyl group],~~



[wherein Ar represents a substituted or unsubstituted phenyl group or a naphthyl group; R represents a C_1 to C_9 alkyl group; and q represents an integer of 2 or 3].

3. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 1, which comprises a curing accelerator for the component (D).

4. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 3, wherein the curing accelerator is a basic compound.

5. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 2, which comprises a curing accelerator for the component (D).

6. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 5, wherein the curing accelerator is a basic compound.

7. **(Original)** A method for formation of a cured article, which comprises applying the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6, subjecting to prebaking, subjecting to selective exposure, subjecting to PEB (post-exposure baking) and subjecting to alkali development to form a resist pattern, followed by melting with heating and further heat curing.

8. **(Original)** A cured article obtainable by the method of claim 7.

9. **(Original)** A method for production of a functional device, which comprises forming a resist pattern of and curing the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6.

10. **(Original)** A functional device obtainable by the method of claim 9.

11. **(New)** A method for formation of a cured article, comprising:

applying a chemically amplified positive photosensitive thermosetting resin composition which comprises (A) an alkali soluble resin, (B) a compound generating an acid under irradiation with radiation, (C) a crosslinking polyvinyl ether compound, and (D) an epoxy resin;

subjecting the composition to prebaking so as to form an alkali-insolubilized resist layer by a crosslinking reaction of the component (C) with the component (A);

subjecting the alkali-insolubilized resist layer to selective exposure so as to decompose the crosslinking between the component (C) with the component (A) by an action of an acid generated from the component (B) upon exposure so that the exposed area becomes alkali soluble while the unexposed area remains alkali insoluble:

subjecting the layer subjected to the selective exposure to post-exposure baking (PEB); and

subjecting the layer subjected to the PEB to alkali development to form a resist pattern, followed by melting with heating and further heat curing by the crosslinking reaction of the component (D) with the component (A).